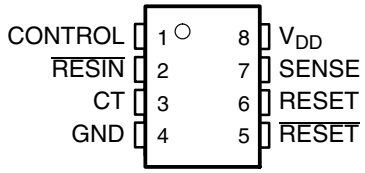
SGLS208A – OCTOBER 2003 – REVISED MAY 2008

- **Qualified for Automotive Applications**
- **Power-On Reset Generator**
- **Automatic Reset Generation After Voltage Drop**
- **Precision Voltage Sensor**
- **Temperature-Compensated Voltage Reference**
- **Programmable Delay Time by External Capacitor**
- **Supply Voltage Range . . . 2 V to 6 V**
- **Defined $\overline{\text{RESET}}$ Output from $V_{DD} \geq 1$ V**
- **Power-Down Control Support for Static RAM With Battery Backup**
- **Maximum Supply Current of 16 μA**
- **Power Saving Totem-Pole Outputs**

PW PACKAGE
(TOP VIEW)



description

The TLC77xx family of micropower supply voltage supervisors provide reset control, primarily in microcomputer and microprocessor systems.

During power-on, $\overline{\text{RESET}}$ is asserted when V_{DD} reaches 1 V. After minimum V_{DD} ($\geq$ 2 V) is established, the circuit monitors SENSE voltage and keeps the reset outputs active as long as SENSE voltage ($V_{I(SENSE)}$) remains below the threshold voltage. An internal timer delays return of the output to the inactive state to ensure proper system reset. The delay time, t_d, is determined by an external capacitor:

$$t_d = 2.1 \times 10^4 \times C_T$$

Where

C_T is in farads

t_d is in seconds

Except for the TLC7701, which can be customized with two external resistors, each supervisor has a fixed SENSE threshold voltage set by an internal voltage divider. When SENSE voltage drops below the threshold voltage, the outputs become active and stay in that state until SENSE voltage returns above threshold voltage and the delay time, t_d, has expired.

In addition to the power-on-reset and undervoltage-supervisor function, the TLC77xx adds power-down control support for static RAM. When CONTROL is tied to GND, RESET will act as active high. The voltage monitor contains additional logic intended for control of static memories with battery backup during power failure. By driving the chip select ($\overline{\text{CS}}$) of the memory circuit with the RESET output of the TLC77xx and with the CONTROL driven by the memory bank select signal ($\overline{\text{CSH1}}$) of the microprocessor (see Figure 10), the memory circuit is automatically disabled during a power loss. (In this application the TLC77xx power has to be supplied by the battery.)

ORDERING INFORMATION†‡

T_A	PACKAGE§		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	TSSOP – PW	Tape and reel	TLC7701QPWRQ1	7701Q1
	TSSOP – PW	Tape and reel	TLC7705QPWRQ1	7705Q1
	TSSOP – PW	Tape and reel	TLC7733QPWRQ1	7733Q1

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

‡ Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

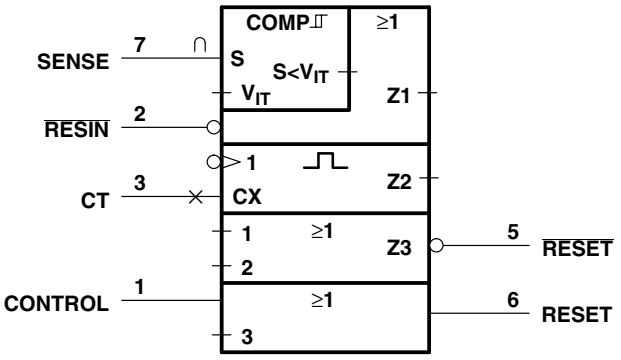
§ The PW package is only available left-end taped and reeled (indicated by the R suffix on the device type; e.g., TLC7701QPWREP).

FUNCTION TABLE

CONTROL	$\overline{\text{RESIN}}$	$V_{I(SENSE)} > V_{IT+}$	RESET	$\overline{\text{RESET}}$
L	L	False	H	L
L	L	True	H	L
L	H	False	H	L
L	H	True	L§	H§
H	L	False	H	L
H	L	True	H	L
H	H	False	H	L
H	H	True	H	H§

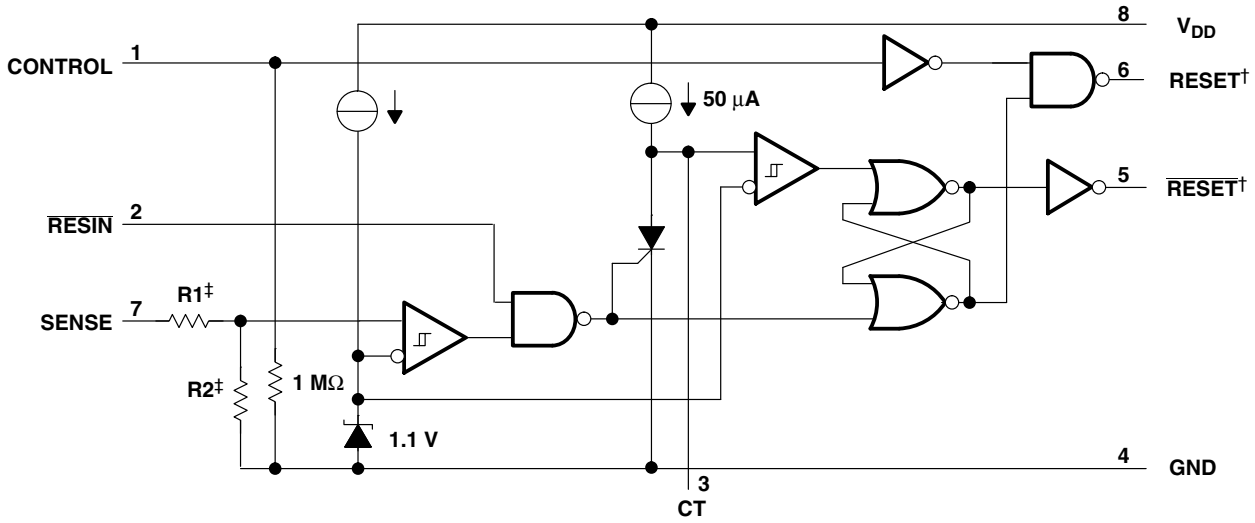
§ RESET and $\overline{\text{RESET}}$ states shown are valid for $t > t_d$.

logic symbol¶



¶ This symbol is in accordance with ANSI/IEEE Std 91–1984 and IEC Publication 617-12.

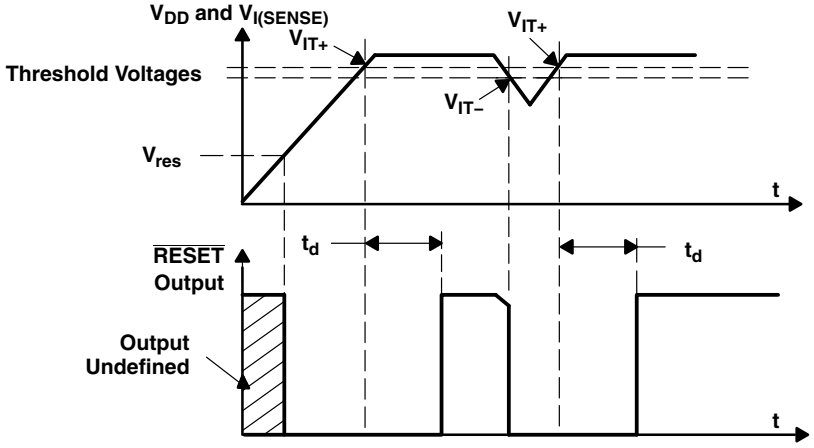
functional block diagram



† Outputs are totem-pole configuration. External pullup or pulldown resistors are not required.
‡ Nominal values:

	R1 (Typ)	R2 (Typ)
TLC7701	0	∞
TLC7705	910 kΩ	290 kΩ
TLC7733	750 kΩ	450 kΩ

timing diagram



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V_{DD} (see Note 1) . . . . . 7 V
Input voltage range, CONTROL, $\overline{RESIN}$, SENSE (see Note 1) . . . . . –0.3 V to 7 V
Maximum low output current, I_{OL} . . . . . 10 mA
Maximum high output current, I_{OH} . . . . . –10 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$) . . . . . ±10 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$) . . . . . ±10 mA
Continuous total power dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A: TL77xxQ . . . . . –40°C to 125°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 85°C$ POWER RATING	$T_A = 125°C$ POWER RATING
PW	525 mW	4.2 mW/°C	273 mW	105 mW

recommended operating conditions at specified temperature range

		MIN	MAX	UNIT
Supply voltage, V_{DD}		2	6	V
Input voltage, V_I		0	V_{DD}	V
High-level input voltage at $\overline{RESIN}$ and CONTROL‡, V_{IH}		$0.7 \times V_{DD}$		V
Low-level input voltage at $\overline{RESIN}$ and CONTROL‡, V_{IL}			$0.2 \times V_{DD}$	V
High-level output current, I_{OH}	$V_{DD} \ge 2.7$ V		–2	mA
Low-level output current, I_{OL}	$V_{DD} \ge 2.7$ V		2	mA
Input transition rise and fall rate at $\overline{RESIN}$ and CONTROL, $\Delta t/\Delta V$			100	ns/V
Operating free-air temperature range, T_A		–40	125	°C

‡ To ensure a low supply current, V_{IL} should be kept < 0.3 V and $V_{IH} > V_{DD} - 0.3$ V.

electrical characteristics over recommended operating conditions (see Note 2) (unless otherwise noted)

PARAMETER				TEST CONDITIONS	TLC77xx			UNIT
					MIN	TYP†	MAX	
V_{OH}	High-level output voltage	I_{OH} = –20 μA		V_{DD} = 2 V	1.8			V
				V_{DD} = 2.7 V	2.5			
				V_{DD} = 4.5 V	4.3			
		I_{OH} = –2 mA		V_{DD} = 4.5 V	3.7			
V_{OL}	Low-level output voltage	I_{OL} = 20 μA		V_{DD} = 2 V			0.2	V
				V_{DD} = 2.7 V			0.2	
				V_{DD} = 4.5 V			0.2	
		I_{OL} = 2 mA		V_{DD} = 4.5 V			0.5	
V_{IT-}	Negative-going input threshold voltage, SENSE (see Note 3)		TLC7701	V_{DD} = 2 V to 6 V	1.04	1.1	1.16	V
			TLC7705		4.43	4.5	4.63	
			TLC7733		2.855	2.93	3.03	
V_{hys}	Hysteresis voltage, SENSE		TLC7701	V_{DD} = 2 V to 6 V		30		mV
			TLC7705			70		
			TLC7733					
V_{res}	Power-up reset voltage‡			I_{OL} = 20 μA			1	V
I_I	Input current	$\overline{RESIN}$		V_I = 0 V to V_{DD}			2	μA
		CONTROL		V_I = V_{DD}		7	15	
		SENSE		V_I = 5 V		5	10	
		SENSE, TLC7701 only		V_I = 5 V			2	
I_{DD}	Supply current			$\overline{RESIN}$ = V_{DD}, SENSE = $V_{DD} \geq V_{IT}$max + 0.2 V, CONTROL = 0 V, Outputs open		9	16	μA
$I_{DD(d)}$	Supply current during t_d			V_{DD} = 5 V, V_{CT} = 0 , $\overline{RESIN}$ = V_{DD}, SENSE = V_{DD}, CONTROL = 0 V, Outputs open		120	150	μA
C_I	Input capacitance, SENSE			V_I = 0 V to V_{DD}		50		pF

† Typical values apply at T_A = 25°C.

‡ The lowest supply voltage at which $\overline{RESET}$ becomes active. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology. Rise time of $V_{DD} \geq 15$ μs/V.

NOTES: 2. All characteristics are measured with C_T = 0.1 μF.

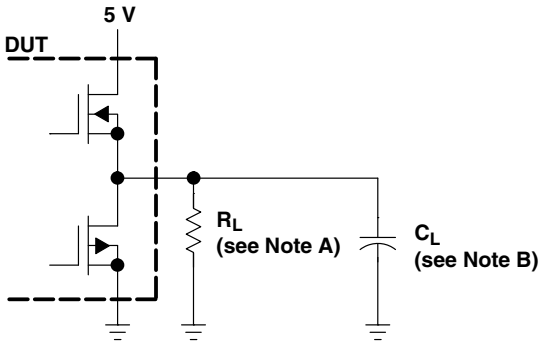
3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μF) should be connected near the supply terminals.

switching characteristics at V_{DD} = 5 V, R_L = 2 kΩ, C_L = 50 pF, T_A = Full Range (unless otherwise noted)

PARAMETER		MEASURED		TEST CONDITIONS	TLC77xx			UNIT
		FROM (INPUT)	TO (OUTPUT)		MIN	TYP	MAX	
t_d	Delay time	$V_{I(SENSE)} \geq V_{IT+}$	RESET and $\overline{\text{RESET}}$	$\overline{\text{RESIN}}$ = 0.7 × V_{DD}, CONTROL = 0.2 × V_{DD}, C_T = 100 nF, T_A = Full range, See timing diagram	1.1	2.1	4.2	ms
t_{PLH}	Propagation delay time, low-to-high-level output	SENSE	$\overline{\text{RESET}}$	V_{IH} = V_{IT+}max + 0.2 V, V_{IL} = V_{IT-}min – 0.2 V, $\overline{\text{RESIN}}$ = 0.7 × V_{DD}, CONTROL = 0.2 × V_{DD}, CT = NC†			20	µs
t_{PHL}	Propagation delay time, high-to-low-level output						5	
t_{PLH}	Propagation delay time, low-to-high-level output		RESET				5	
t_{PHL}	Propagation delay time, high-to-low-level output						20	
t_{PLH}	Propagation delay time, low-to-high-level output	$\overline{\text{RESIN}}$	$\overline{\text{RESET}}$	V_{IH} = 0.7 × V_{DD}, V_{IL} = 0.2 × V_{DD}, SENSE = V_{IT+}max + 0.2 V, CONTROL = 0.2 × V_{DD}, CT = NC†			20	µs
t_{PHL}	Propagation delay time, high-to-low-level output						60	ns
t_{PLH}	Propagation delay time, low-to-high-level output		RESET				65	
t_{PHL}	Propagation delay time, high-to-low-level output						20	µs
t_{PLH}	Propagation delay time, low-to-high-level output	CONTROL	RESET	V_{IH} = 0.7 × V_{DD}, V_{IL} = 0.2 × V_{DD}, SENSE = V_{IT+}max + 0.2 V, $\overline{\text{RESIN}}$ = 0.7 × V_{DD}, CT = NC†			58	ns
t_{PHL}	Propagation delay time, high-to-low-level output						58	ns
	Low-level minimum pulse duration to switch RESET and $\overline{\text{RESET}}$	SENSE		V_{IH} = V_{IT+}max + 0.2 V, V_{IL} = V_{IT-}min – 0.2 V,	3			µs
		$\overline{\text{RESIN}}$		V_{IL} = 0.2 × V_{DD}, V_{IH} = 0.7 × V_{DD}	1			
t_r	Rise time		RESET and $\overline{\text{RESET}}$	10% to 90%		8		ns/V
t_f	Fall time			90% to 10%		4		

† NC = No capacitor, and includes up to 100-pF probe and jig capacitance.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. For switching characteristics, R_L = 2 kΩ.
B. C_L = 50 pF includes jig and probe capacitance.

Figure 1. RESET AND $\overline{\text{RESET}}$ Output Configurations

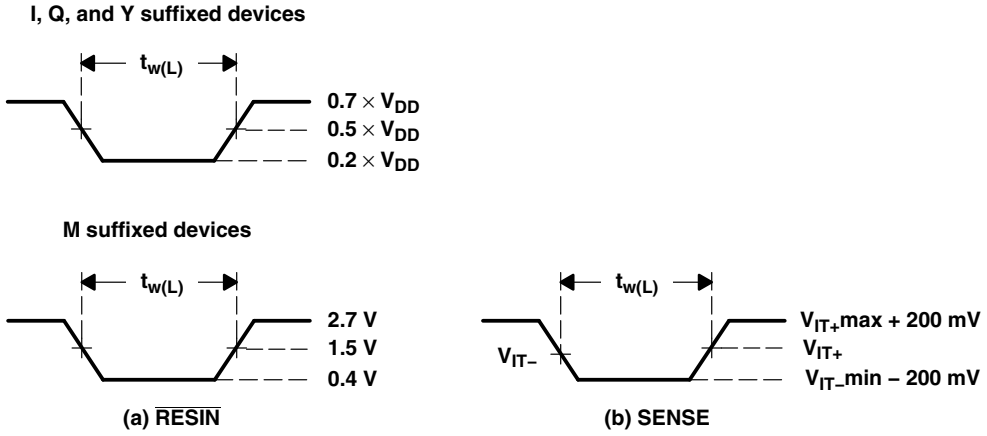


Figure 2. Input Pulse Definition Waveforms

TYPICAL CHARACTERISTICS

NORMALIZED INPUT THRESHOLD VOLTAGE vs TEMPERATURE

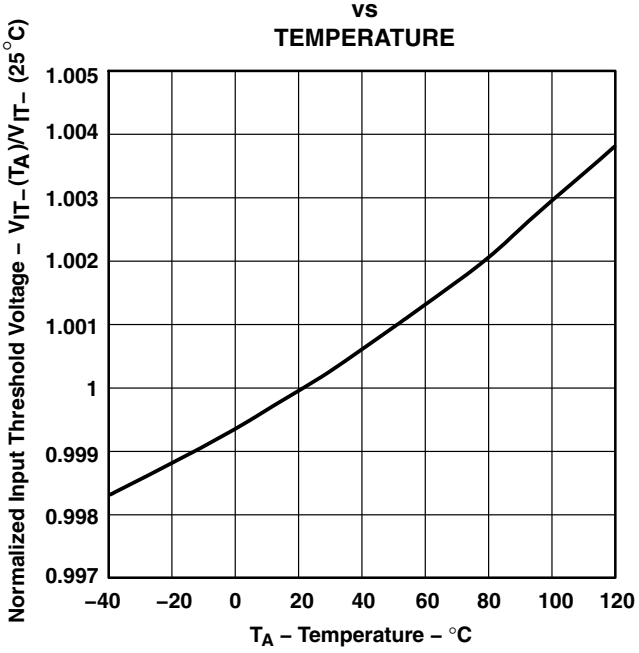


Figure 3

SUPPLY CURRENT vs SUPPLY VOLTAGE

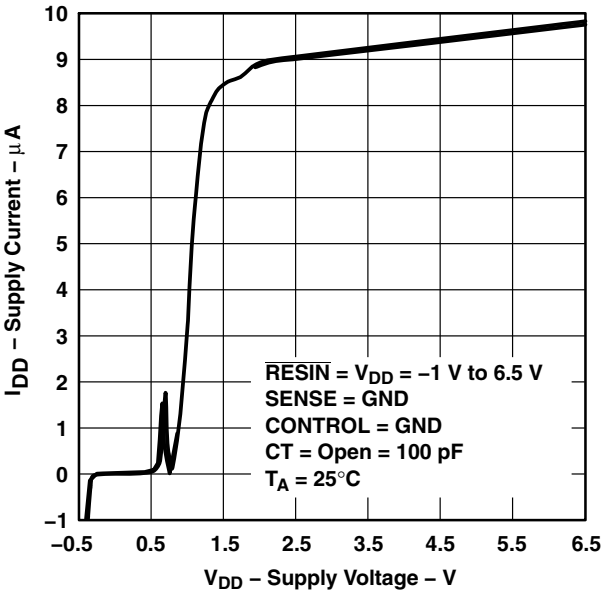


Figure 4

HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT

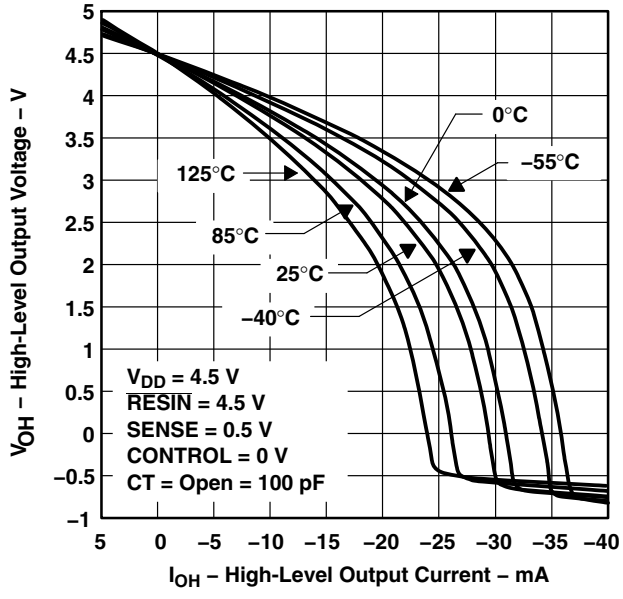


Figure 5

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

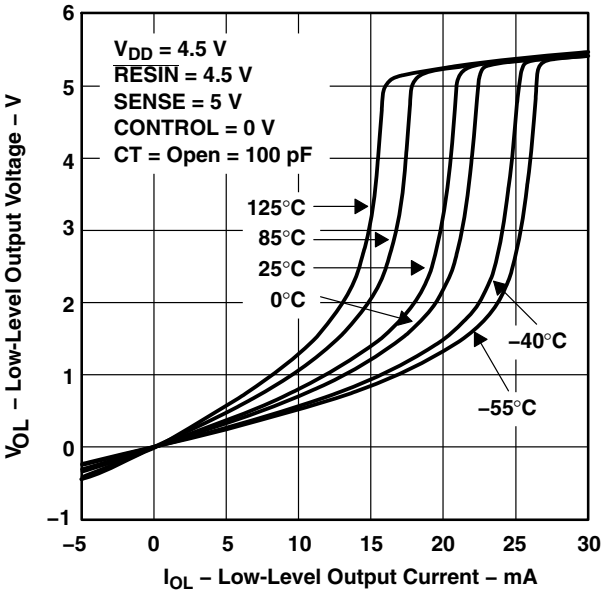


Figure 6

TYPICAL CHARACTERISTICS

**INPUT CURRENT
vs
INPUT VOLTAGE AT SENSE**

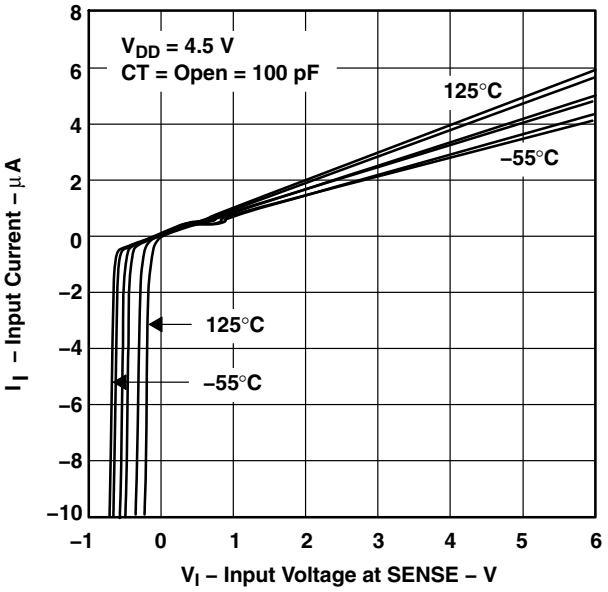


Figure 7

**MINIMUM PULSE DURATION AT SENSE
vs
SENSE THRESHOLD OVERDRIVE**

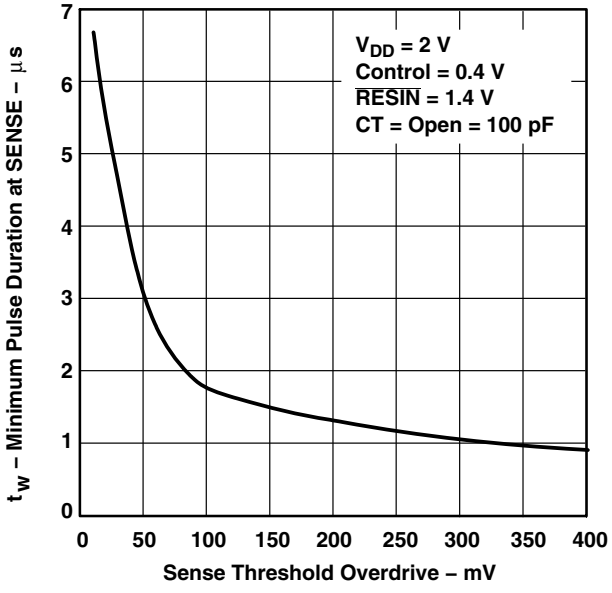


Figure 8

APPLICATION INFORMATION

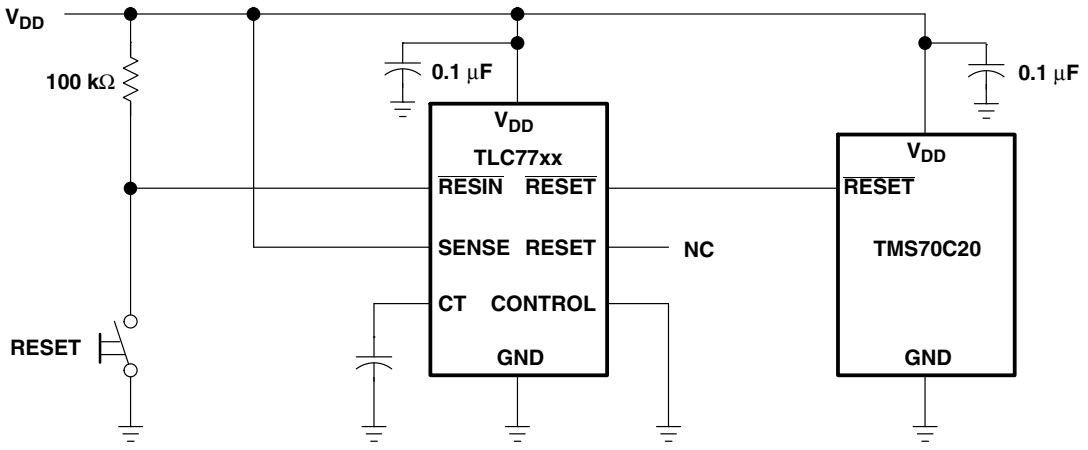


Figure 9. Reset Controller in a Microcomputer System

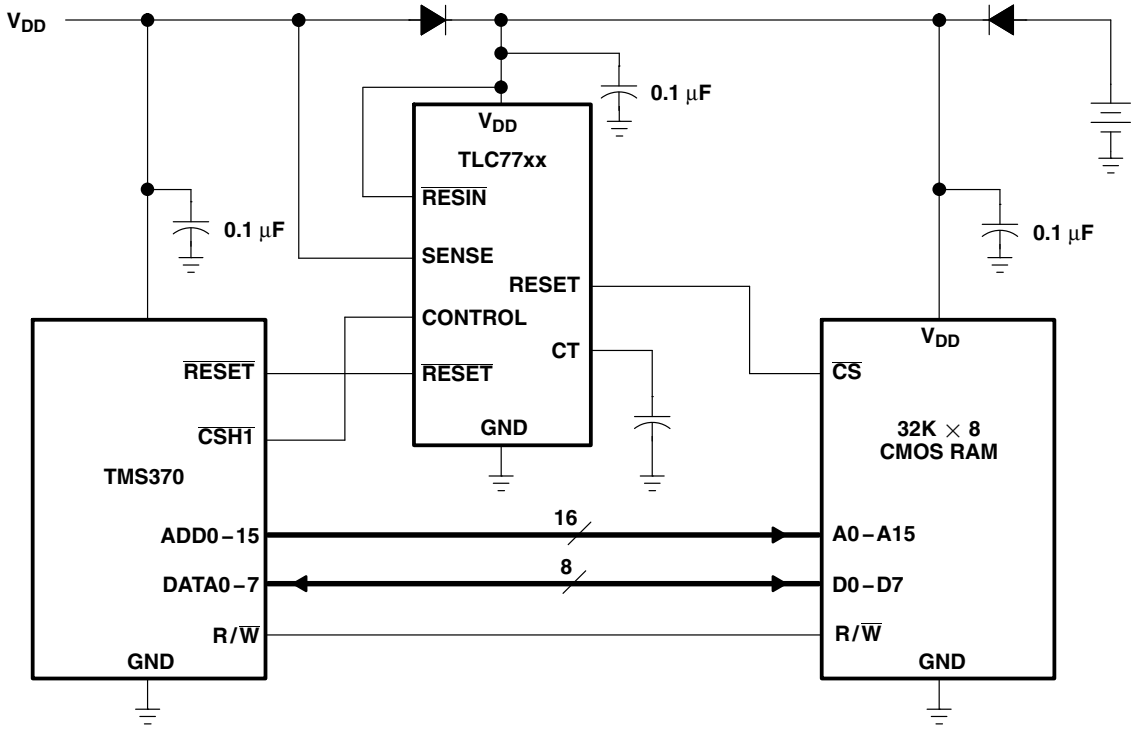


Figure 10. Data Retention During Power Down Using Static CMOS RAMs

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLC7701QPWRQ1	Active	Production	TSSOP (PW) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	7701Q1
TLC7705QPWRG4Q1	Obsolete	Production	TSSOP (PW) | 8	-	-	Call TI	Call TI	-40 to 125	7705Q1
TLC7733QPWRQ1	Active	Production	TSSOP (PW) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	7733Q1

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF TLC77-Q1 :

- Catalog : TLC77

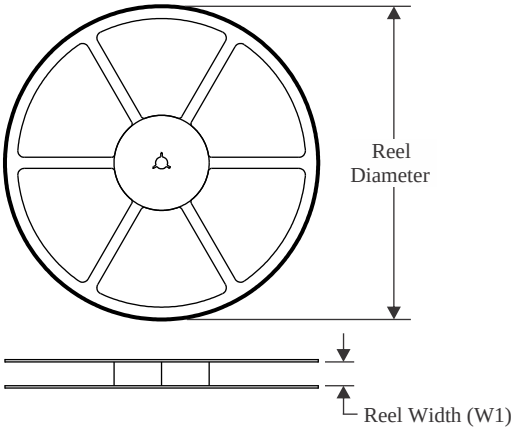
- Enhanced Product : TLC77-EP

NOTE: Qualified Version Definitions:

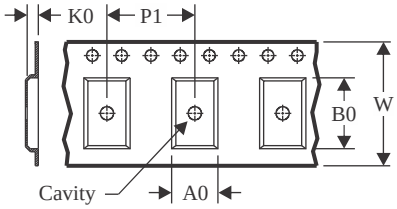
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

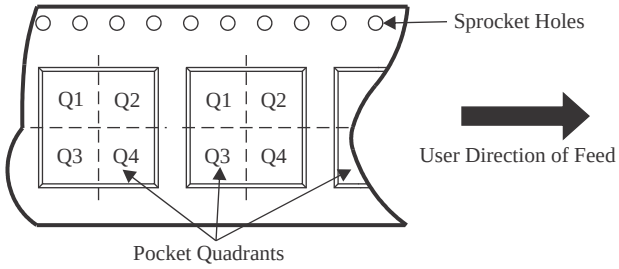


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

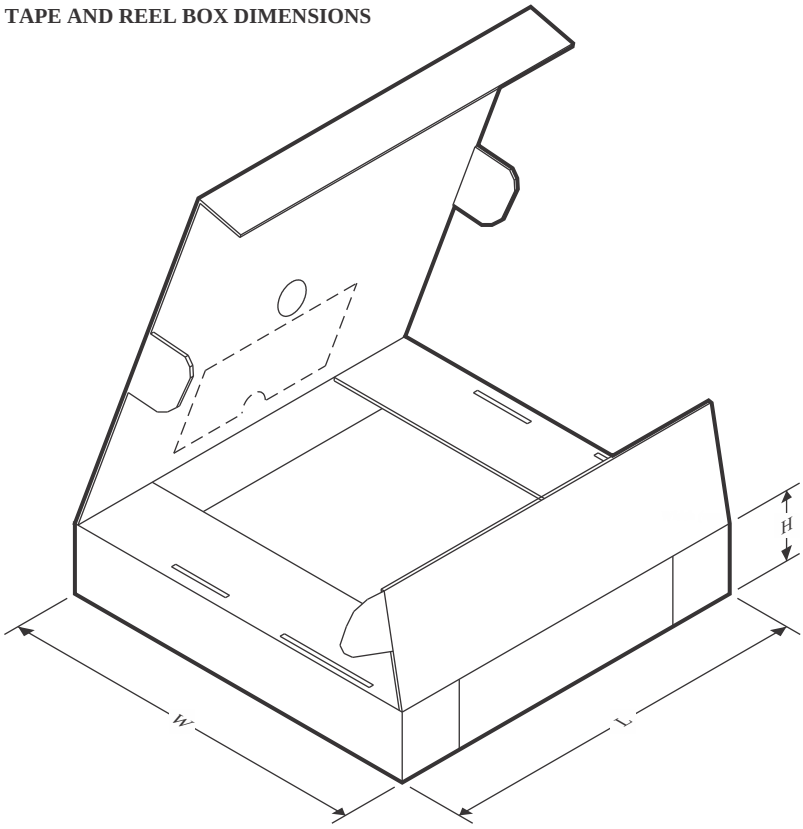
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC7701QPWRQ1	TSSOP	PW	8	2500	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7733QPWRQ1	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

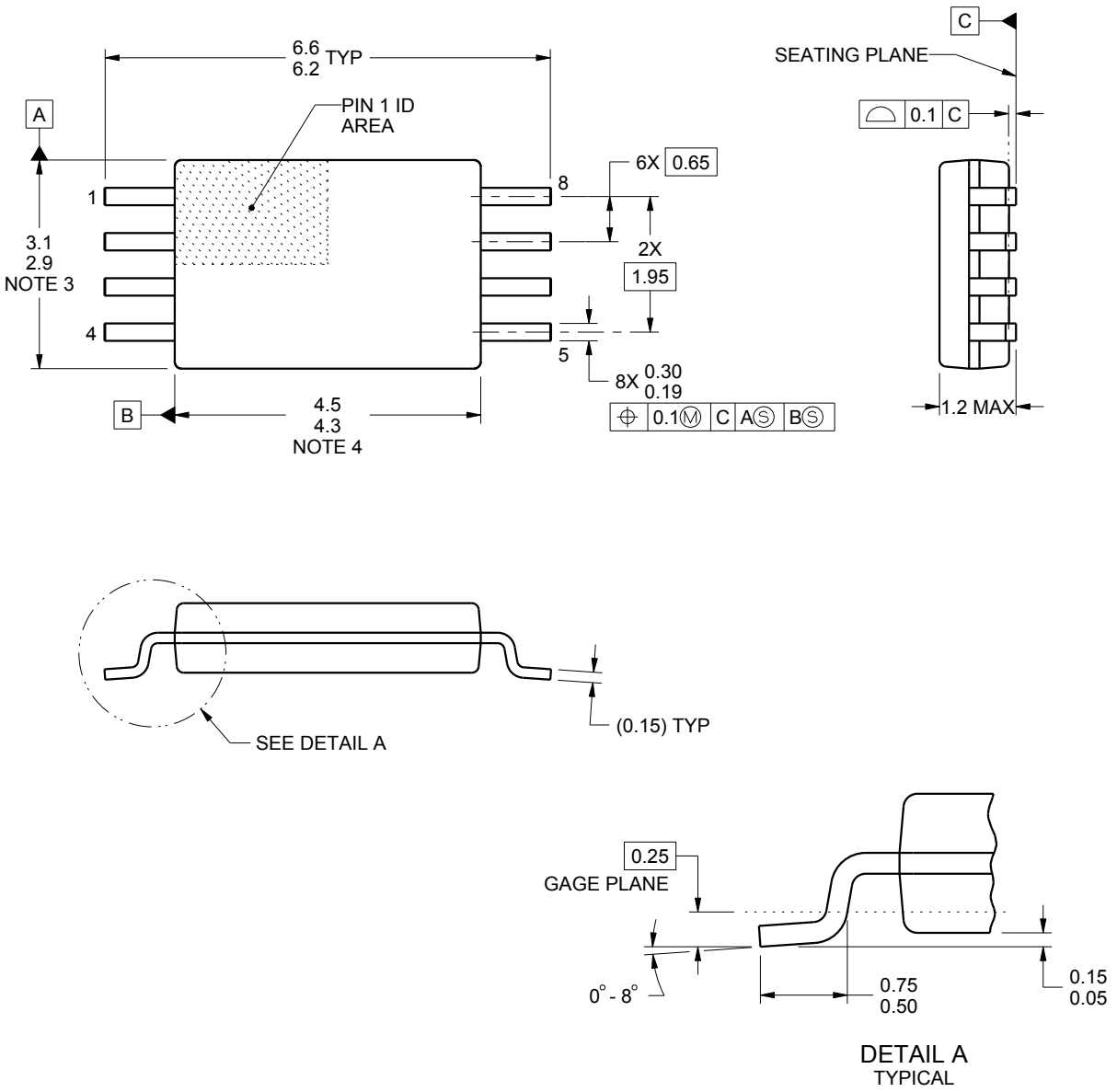
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC7701QPWRQ1	TSSOP	PW	8	2500	356.0	356.0	35.0
TLC7733QPWRQ1	TSSOP	PW	8	2000	356.0	356.0	35.0

PACKAGE OUTLINE

PW0008A

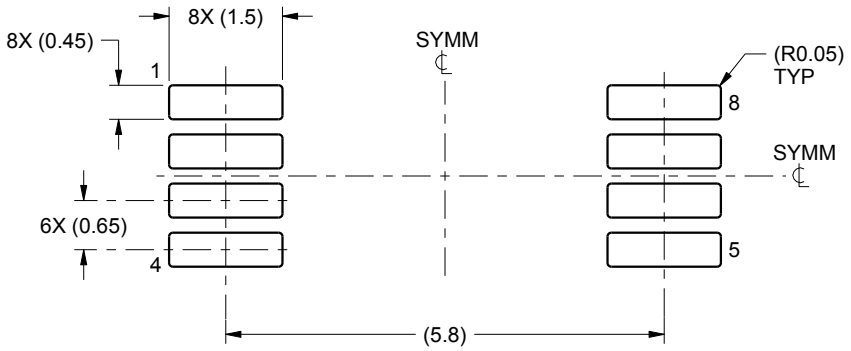
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

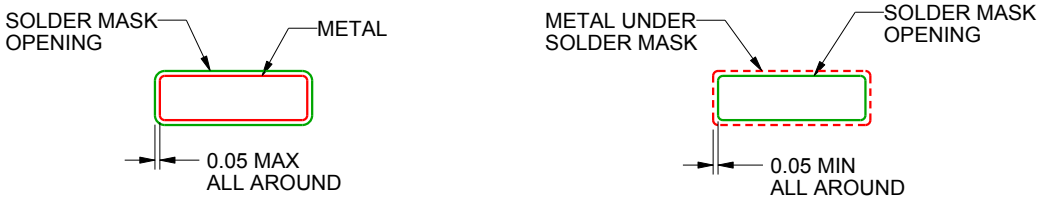


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

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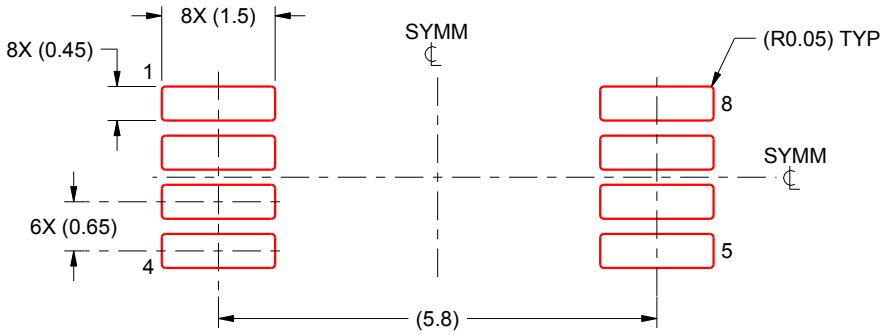
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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